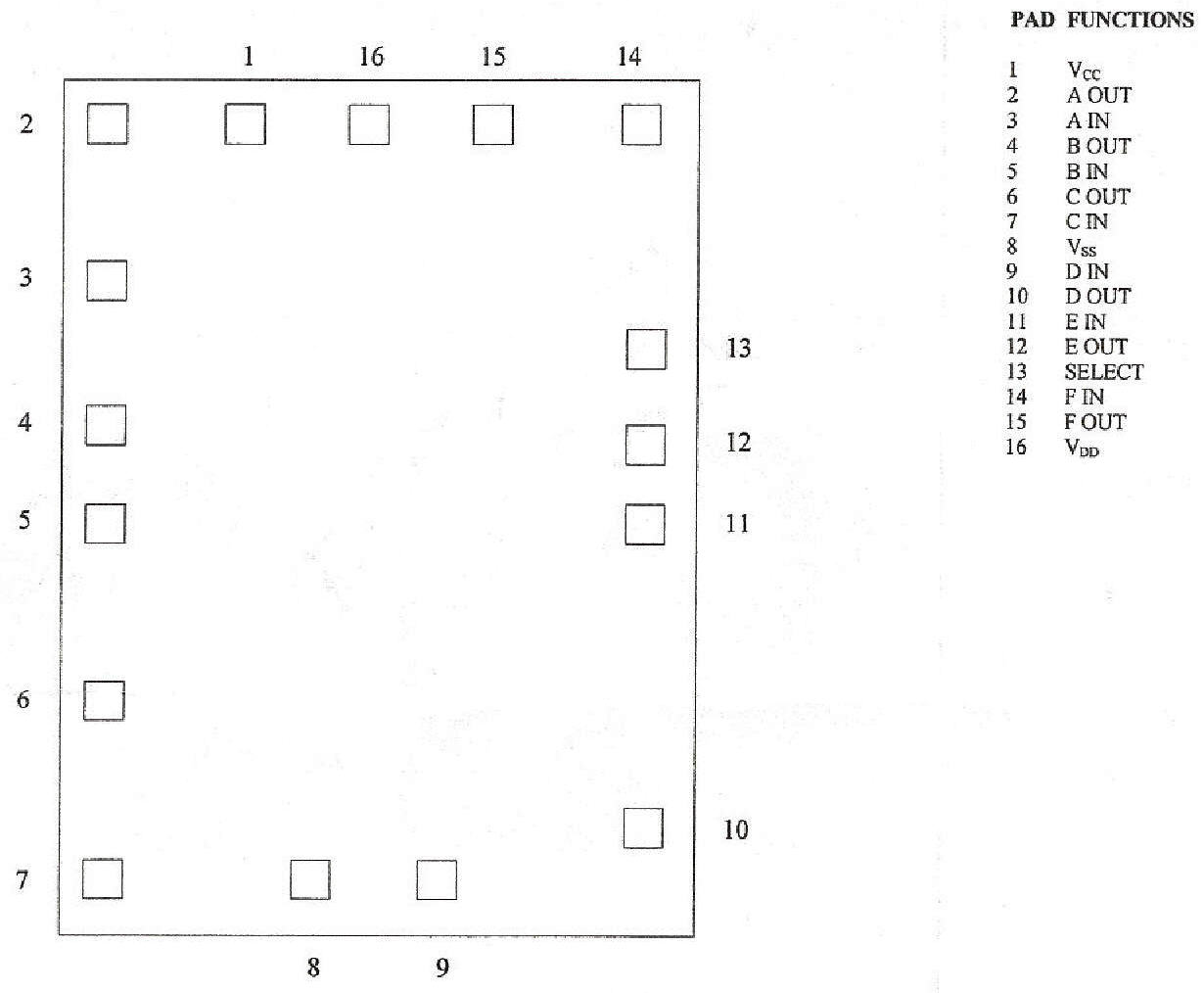
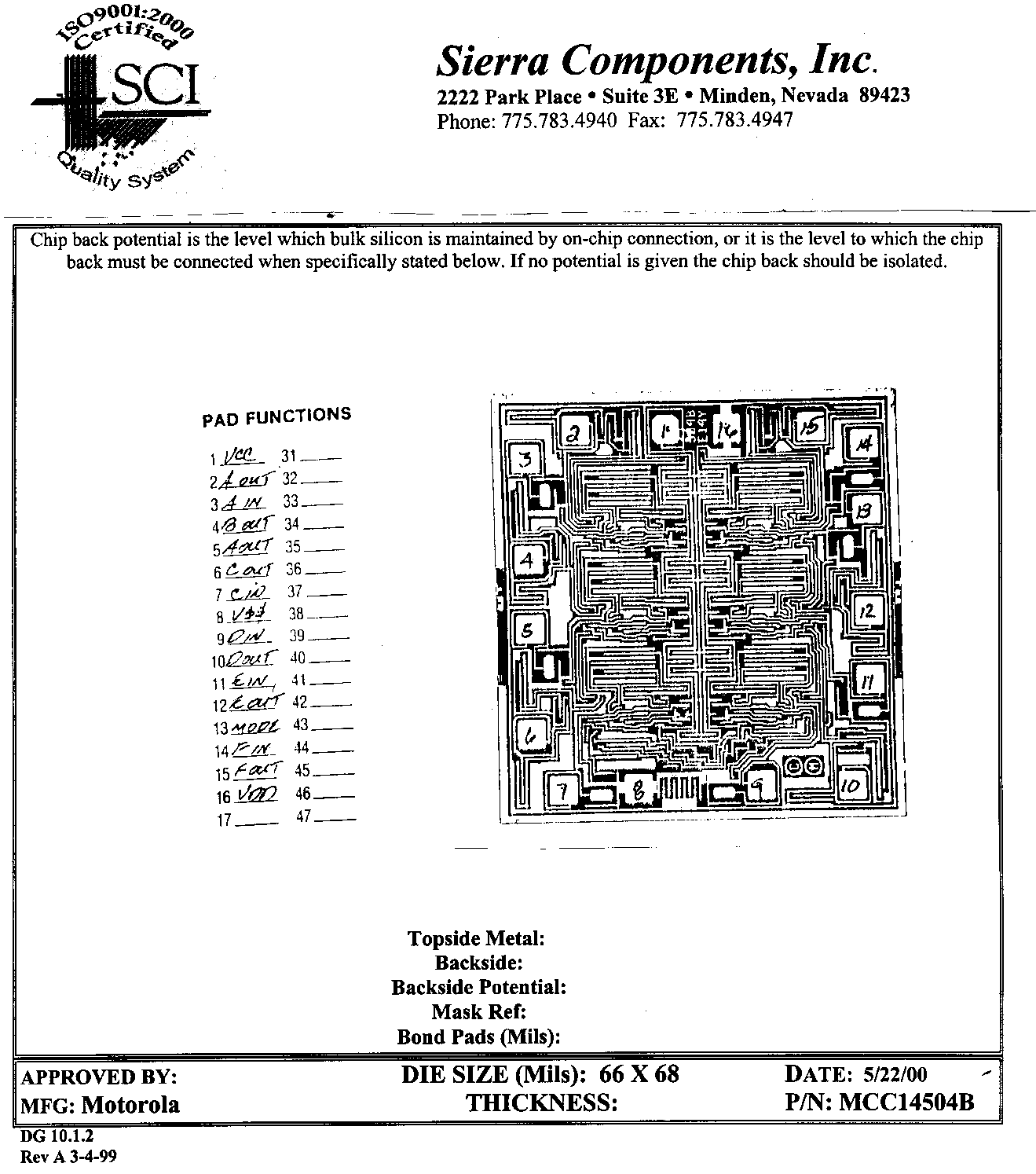
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

****

****

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .066” X .068” DATE: 7/22/21**

**MFG: MOTOROLA THICKNESS .010” P/N: CD4504B**

**DG 10.1.2**

#### Rev B, 7/19/02